

ABSTRACT

A method for forming a thick film pattern, the method being capable of forming a thick film pattern having a large thickness, a high hardness, and a high aspect ratio and exhibiting high dimension precision and high shape precision, a method for manufacturing an electronic component by using the thick film pattern, and a photolithography photosensitive paste to be used for forming a thick film pattern by using photolithography are provided.

A photosensitive paste containing an inorganic powder, a photosensitive monomer, and a photopolymerization initiator and containing substantially no polymer is applied to a support so as to form a photosensitive paste film, the resulting photosensitive paste film is subjected to an exposure treatment and, thereafter, development is conducted so as to form a predetermined thick film pattern.

Alternatively, a photolithography photosensitive paste containing an inorganic powder, a photosensitive monomer, a photopolymerization initiator, and a polymer is used, wherein a ratio (weight ratio) of the photosensitive monomer to a total amount of the photosensitive monomer and the polymer is 0.86 or more.